

PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT														
NATURE OF CONVEYANCE:	ASSIGNMENT														
CONVEYING PARTY DATA															
<table border="1" style="width: 100%; border-collapse: collapse;"> <thead> <tr> <th style="width: 70%;">Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>Michiko TAKEI</td> <td>06/08/2011</td> </tr> <tr> <td>Yasumori FUKUSHIMA</td> <td>06/03/2011</td> </tr> <tr> <td>Kazuhide TOMIYASU</td> <td>06/03/2011</td> </tr> <tr> <td>Shin MATSUMOTO</td> <td>06/09/2011</td> </tr> <tr> <td>Kazuo NAKAGAWA</td> <td>06/10/2011</td> </tr> <tr> <td>Yutaka TAKAFUJI</td> <td>06/01/2011</td> </tr> </tbody> </table>		Name	Execution Date	Michiko TAKEI	06/08/2011	Yasumori FUKUSHIMA	06/03/2011	Kazuhide TOMIYASU	06/03/2011	Shin MATSUMOTO	06/09/2011	Kazuo NAKAGAWA	06/10/2011	Yutaka TAKAFUJI	06/01/2011
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<table border="1" style="width: 100%; border-collapse: collapse;"> <tr> <td style="width: 20%;">Name:</td> <td>Sharp Kabushiki Kaisha</td> </tr> <tr> <td>Street Address:</td> <td>22-22, Nagaike-cho, Abeno-ku, Osaka-shi</td> </tr> <tr> <td>City:</td> <td>Osaka</td> </tr> <tr> <td>State/Country:</td> <td>JAPAN</td> </tr> <tr> <td>Postal Code:</td> <td>545-8522</td> </tr> </table>		Name:	Sharp Kabushiki Kaisha	Street Address:	22-22, Nagaike-cho, Abeno-ku, Osaka-shi	City:	Osaka	State/Country:	JAPAN	Postal Code:	545-8522				
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CORRESPONDENCE DATA															
<p>Fax Number: (240)238-2825 <i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i></p> <p>Phone: 408-530-8033 Email: patents@cyiplaw.com Correspondent Name: Masao Yoshimura, Chen Yoshimura LLP Address Line 1: 333 W. El Camino Real Address Line 2: Suite 380 Address Line 4: Sunnyvale, CALIFORNIA 94087</p>															
ATTORNEY DOCKET NUMBER:	87427.09R00813US														

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PATENT
REEL: 026477 FRAME: 0074

NAME OF SUBMITTER:

Masao Yoshimura

Total Attachments: 4

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ASSIGNMENT

WHEREAS I/We, the below named inventor(s), [hereinafter referred to as Assignor(s)], have made an invention entitled:

SEMICONDUCTOR DEVICE AND METHOD FOR MANUFACTURING SAME

for which I/WE executed an application for United States Letters Patent concurrently herewith; or filed a PCT International Application designating the United States on August 21, 2009, (PCT International Application No. PCT/JP2009/004039); and

WHEREAS, Sharp Kabushiki Kaisha, a corporation of Japan, whose post office address is 22-22, Nagaike-cho, Abeno-ku, Osaka-shi, Osaka 545-8522 Japan, (hereinafter referred to as Assignee), is desirous of securing the entire right, title, and interest in and to this invention, the application for United States Letters Patent on this invention and the Letters Patent to issue upon this application;

NOW THEREFORE, be it known that, for good and valuable consideration the receipt of which from Assignee is hereby acknowledged, I/WE, as Assignor(s), have sold, assigned, transferred, and set over, and do hereby sell, assign, transfer, and set over unto the Assignee, its lawful successors and assigns, MY/OUR entire right, title, and interest in and to this invention and this application, and all divisions, and continuations thereof, and all Letters Patent of the United States which may be granted thereon, and all reissues thereof; and I/WE hereby authorize and request the Commissioner of Patents and Trademarks of the United States to issue all Letters Patent for this invention to Assignee, its successors and assigns, in accordance with the terms of this Assignment;

AND, I/WE HEREBY further covenant and agree that I/WE will, without further consideration, communicate with Assignee, its successors and assigns, any facts known to ME/US respecting this invention and testify in any legal proceeding, sign all lawful papers when called upon to do so, execute and deliver all papers that may be necessary or desirable to perfect the title to this invention in said Assignee, its successors and assigns, execute all divisional, continuation, and reissue applications, make all rightful oaths and generally do everything possible to aid Assignee, its successors and assigns, to obtain and enforce proper patent protection for this invention in the United States, it being understood that any expense incident to the execution of such papers shall be borne by the Assignee, its successors and assigns.

AND, I/WE HEREBY authorize and request the attorneys I/WE have empowered in the Power of Attorney in this application, to insert here in parenthesis (Application No. _____, filed _____) the filing date and application number of said application when known.

IN TESTIMONY WHEREOF, I/WE have hereunto set our hand(s).

Full Name of Sole or First Assignor Michiko TAKEI	Assignor's Signature <i>Michiko Takei</i>	Date <i>June 8, 2011</i>
Address c/o Sharp Kabushiki Kaisha 22-22, Nagaike-cho, Abeno-ku, Osaka-shi, Osaka 545-8522 Japan		Citizenship Japan
Full Name of Second Assignor Yasunori FUKUSHIMA	Assignor's Signature <i>Yasunori Fukushima</i>	Date <i>June 3, 2011</i>
Address c/o Sharp Kabushiki Kaisha 22-22, Nagaike-cho, Abeno-ku, Osaka-shi, Osaka 545-8522 Japan		Citizenship Japan
Names of additional inventors attached <input checked="" type="checkbox"/> Yes <input type="checkbox"/> No		

Full Name of Third Assignor Kazuhide TOMIYASU	Assignor's Signature <i>Kazuhide Tomiyasu</i>	Date June 3, 2011
Address c/o Sharp Kabushiki Kaisha 22-22, Nagaïke-cho, Abeno-ku, Osaka-shi, Osaka 545-8522 Japan		Citizenship Japan
Full Name of Fourth Assignor Shin MATSUMOTO	Assignor's Signature <i>Shin Matsumoto</i>	Date June 9, 2011
Address c/o Sharp Kabushiki Kaisha 22-22, Nagaïke-cho, Abeno-ku, Osaka-shi, Osaka 545-8522 Japan		Citizenship Japan
Full Name of Fifth Assignor Kazuo NAKAGAWA	Assignor's Signature <i>Kazuo Nakagawa</i>	Date June 10, 2011
Address c/o Sharp Kabushiki Kaisha 22-22, Nagaïke-cho, Abeno-ku, Osaka-shi, Osaka 545-8522 Japan		Citizenship Japan
Full Name of Sixth Assignor Yutaka TAKAFUJI	Assignor's Signature	Date
Address c/o Sharp Kabushiki Kaisha 22-22, Nagaïke-cho, Abeno-ku, Osaka-shi, Osaka 545-8522 Japan		Citizenship Japan

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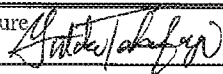
NOW THEREFORE, be it known that, for good and valuable consideration the receipt of which from Assignee is hereby acknowledged, I/WE, as Assignor(s), have sold, assigned, transferred, and set over, and do hereby sell, assign, transfer, and set over unto the Assignee, its lawful successors and assigns, MY/OUR entire right, title, and interest in and to this invention and this application, and all divisions, and continuations thereof, and all Letters Patent of the United States which may be granted thereon, and all reissues thereof; and I/WE hereby authorize and request the Commissioner of Patents and Trademarks of the United States to issue all Letters Patent for this invention to Assignee, its successors and assigns, in accordance with the terms of this Assignment;

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Full Name of Sixth Assignor Yutaka TAKAFUJI	Assignor's Signature 	Date 06/01/2011
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